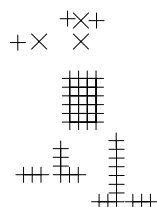


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NOTES

MATERIAL: FR4 1 OZ COPPER EACH LAYER.
 ALL HOLES PLATED THRU WITH 1 OZ COPPER MIN.
 FINAL COPPER ON EXTERNAL LAYERS = 2 OZ. MINIMUM.

For best thermal performance,
 Make GND copper as large as
 possible, except on layer 1
 directly under U1.



All footprints and spacings have been set
 according to common PCB fabrication
 and assembly practices. If necessary,
 these spacings can be modified according to
 customer manufacturing capabilities.

SIZE	QTY	SYM	PLATED	TOL
8	49	+	YES	NOTE
16	3	×	YES	STD

NOTE: USE 13 MIL DRILL FOR 8 MIL PLTD HOLES
 PLUGGING/FILLING OF THESE HOLES IS ACCEPTABLE.

EN5367QI Critical Component Circuit

This layout only shows the critical components
 and traces for minimum footprint with ENABLE
 tied to VIN.

Alternate ENABLE configurations, & other small-
 signal pins need to be connected and routed
 according to the specific customer application.

Solder mask and paste layer openings should be
 reviewed and optimized to meet customer
 PCB fabrication and assembly guidelines.

Gerber Format: RS274X, 3.5
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DRAWN BY	DATE	06992, EN5367QI SOLUTION FAB			
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